Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1. (Original) A circuit device comprising:

first conductive patterns, separated by first separation grooves;

second conductive patterns, formed more thinly than the first conductive patterns and separated by second separation grooves;

first circuit element, affixed onto the first conductive patterns;

second circuit element, affixed onto the second conductive patterns; and

an insulating resin, covering the circuit element and the conductive patterns while leaving rear surfaces of both of the conductive patterns exposed and filling both of the separation grooves.

2. (Original) The device of Claim 1, wherein top surfaces of the first conductive patterns are formed higher than top surfaces of the second conductive patterns.

3. (Original) The device of Claim 1, wherein at least one constricted part is provided at a side part of each separation groove that separates the first conductive patterns.

4. (Original) The device of Claim 1, wherein the second circuit elements are thicker than the first circuit elements.

5. (Currently amended) The device of Claim 1, wherein [[the]] a sum height of [[the]] a height of the first circuit element and [[the]] a height of the first conductive patterns is made

equivalent to [[the]] a sum height of [[the]] a height of the second circuit element and [[the]] a height of the second conductive patterns.

6. (Currently amended) The device of Claim 1, wherein the first circuit element [[is]] comprises a semiconductor element.

7. (Currently amended) The device of Claim 1, wherein the first circuit element is an element that ~~accompany the generation of~~ generates heat.

8. (Currently amended) The device of Claim 1, wherein the second circuit element [[is]] comprises a chip capacitor.

9. (Original) The device of Claim 1, wherein wiring parts are formed by the second conductive patterns.

10. (Original) A circuit device comprising:

first conductive patterns, separated by first separation grooves;

second conductive patterns, formed more thinly than the first conductive patterns, separated by second separation grooves, and forming wiring;

circuit element, affixed onto the first conductive patterns; and

an insulating resin, covering the circuit element and the conductive patterns while leaving the rear surfaces of both of the conductive patterns exposed and filling both of the separation grooves.

11. (Currently amended) The device of Claim 10, wherein [[the]] top surfaces of the first conductive patterns are formed higher than [[the]] top surfaces of the second conductive patterns.

12. (Original) The device of Claim 10, wherein at least one constricted part is provided at a side part of each separation groove that separates the first conductive patterns.

13. (Currently amended) The device of Claim 10, wherein the circuit element [[is]] comprises a semiconductor element.

14. (Currently amended) The device of Claim 10, wherein the circuit element [[are]] is an element that ~~accompany the generation of~~ generates heat.

15-17. (Canceled)